

ABSTRACT

METHOD FOR COMPRESSION-MOLDING ELECTRONIC PARTS, AND MOLD
SYSTEM

5 In the process of supplying a granular resin 6 into a lower-die cavity 5, the reliability
of the amount of resin supplied into lower-die cavity 5 is efficiently improved by the
following method: The bottom side of a resin-receiving plate 21 having an opening section
37 corresponding to the lower-die cavity 5 is covered with a mold release film 11 to obtain a
resin-supplying plate 21a in which the opening section 37 functions as a resin-receiving
10 section 22. A required amount of granular resin 6 is supplied into the resin-receiving section
22 and then formed into a flat layer (with a uniform thickness) to obtain a resin-flat-loaded
plate 25. Next, the resin-flat-loaded plate 25 is set at the position of the lower-die cavity 5,
and the mold release film 11 is pulled into the lower-die cavity 5 so that the required amount
of flattened granular resin 6 is made to fall together with the mold release film 11 and
15 supplied into the cavity 5 covered with the mold release film 11.

[Figure 4]